

## HRW0203A

### Silicon Schottky Barrier Diode for Rectifying

REJ03G0154-0400Z  
(Previous: ADE-208-014C)  
Rev.4.00  
Jan.06.2004

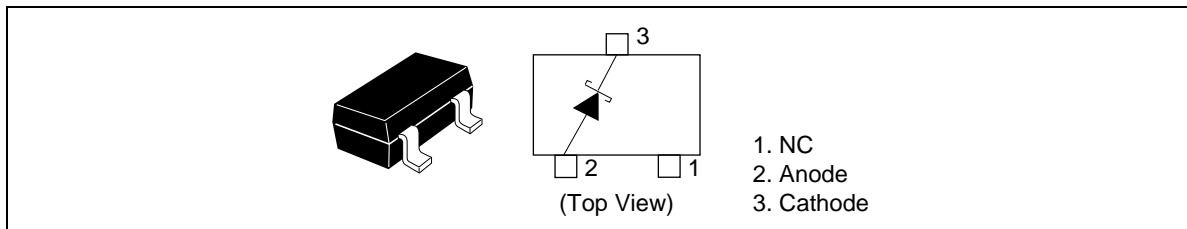
#### Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- MPAK package is suitable for high density surface mounting and high speed assembly.

#### Ordering Information

Type No.	Laser Mark	Package Code
HRW0203A	S5	MPAK

#### Pin Arrangement



**Absolute Maximum Ratings**

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	$V_{RRM}^{*1}$	30	V
Average rectified current	$I_O^{*1}$	200	mA
Non-Repetitive peak forward surge current	$I_{FSM}^{*2}$	2	A
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Notes: 1. See from Fig.1 to Fig.5, with polyimide board.  
2. 50 Hz sine wave 1 pulse.

**Electrical Characteristics**

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	$V_F$	—	—	0.5	V	$I_F = 200 \text{ mA}$
Reverse current	$I_R$	—	—	50	$\mu\text{A}$	$V_R = 30 \text{ V}$
Capacitance	C	—	40	—	pF	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$

Main Characteristics

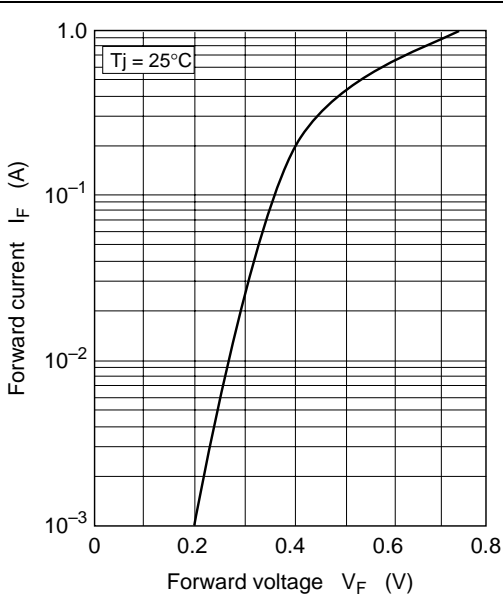


Fig.1 Forward current vs. Forward voltage

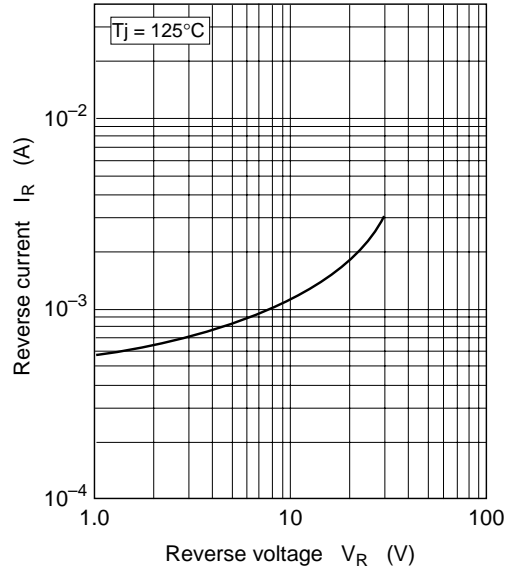


Fig.2 Reverse current vs. Reverse voltage

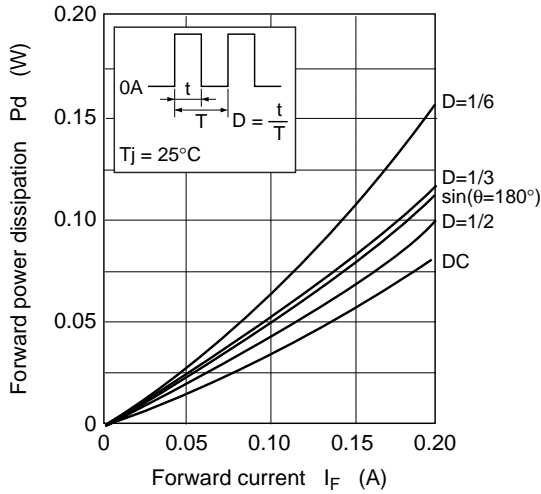


Fig.3 Forward power dissipation vs. Forward current

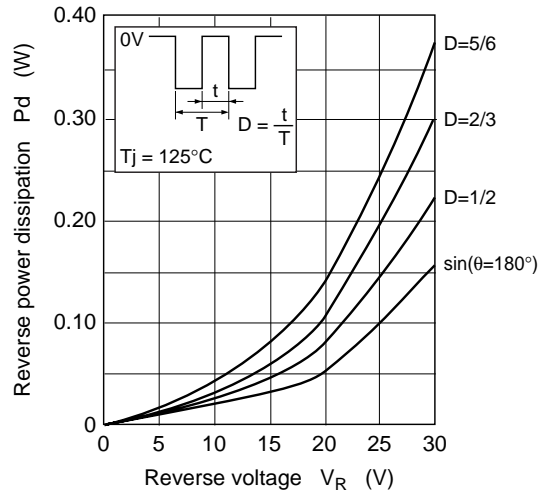


Fig.4 Reverse power dissipation vs. Reverse voltage

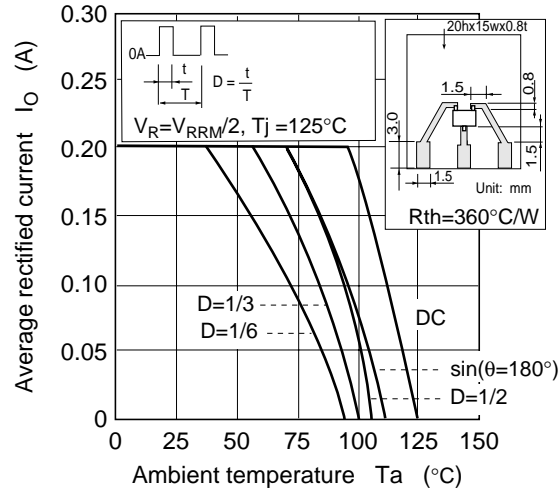


Fig.5 Average rectified current vs. Ambient temperature

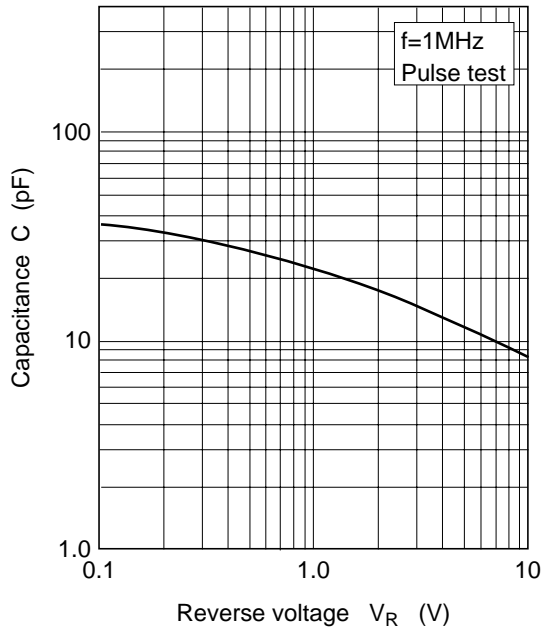
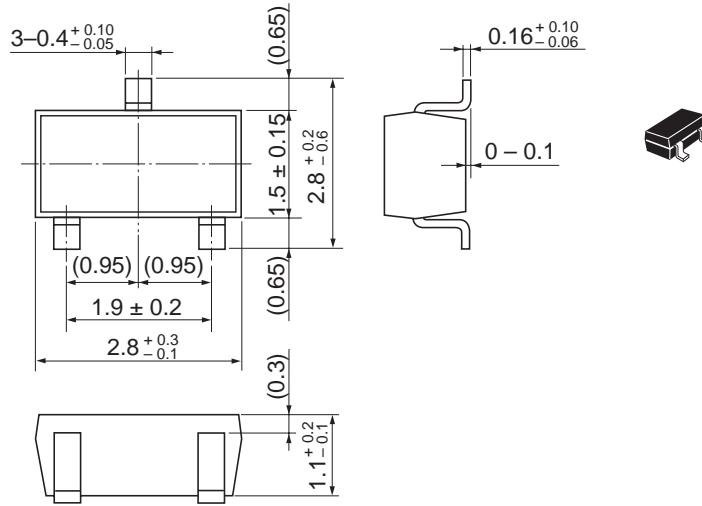


Fig.6 Capacitance vs. Reverse voltage

Package Dimensions

As of January, 2003  
Unit: mm



Package Code	MPAK
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.011 g

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